



## Final Product Change Notification

201907002F01

**Issue Date:** 23-Dec-2019

**Effective Date:** 22-Mar-2020

Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

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# QUALITY

### Management Summary

Bump site release of Chipbond-KF (plated bump) for product types in fcQFN (SOT1232)

#### Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

Bump Site Transfer ASE-KH (Printed Bump) to Chipbond-KF (Plated Bump) for Products in SOT1232 (fcQFN)

### Description of Change

Bump site release of plated bump process of Chipbond-KF for product types in fcQFN (SOT1232) .

#### Reason for Change

Release of plated bump technology is required in view of supply contingency and phasing out of present solder paste and printed bump process technology.

#### Identification of Affected Products

Product identification does not change

### Product Availability

## Sample Information

Samples are available upon request

## Production

Planned first shipment 01-Apr-2020

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

## Data Sheet Revision

No impact to existing datasheet

## Disposition of Old Products

Existing inventory will be shipped until depleted

As same 12 NC is used, during transition phase as well as plated and printed will be delivered.

### Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)



### Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 22-Jan-2020.

### Remarks

Updated PQP are available based on request.

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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